



100% Material Declaration Data Sheet FFG1156

PK397 (v1.2) March 29, 2013

Average Weight: 11.0927g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die				Silicon IC	0.77363	6.974
	Doped silicon	7440-21-3	100.00	Basis	0.77363	
Solder Bump				Die to package	0.258210	2.328
	Tin (Sn)	7440-31-5	63.00	Basis	0.162672	
	Lead (Pb)	7439-92-1	37.00	Basis	0.095538	
Die Underfill					0.130000	1.172
	Bisphenol F-type liquid epoxy resin	9003-36-5	15.00	Basis	0.019500	
	Phenolic resin	Trade secret	15.00	Basis	0.019500	
	Bisphenol A-type liquid epoxy resin	25068-38-6	5.00	Basis	0.006500	
	Amine type accelerator	Trade secret	5.00	Basis	0.006500	
	Silicon dioxide	60676-86-0	54.00	Basis	0.070200	
	Carbon black	1333-86-4	1.00	Basis	0.001300	
	Additives	Trade secret	5.000	Basis	0.006500	
Heat Spreader					4.989300	44.978
	Copper (Cu)	7440-50-8	98.65	Main material	4.921944	
	Nickel (Ni)	7440-02-0	1.35	Main material	0.067356	
Heat Spreader Adhesive					0.152000	1.370
	Organopolysiloxane mixture	N/A	100.00	Main material	0.152000	
Substrate					3.743000	33.743
	Copper	7440-50-8	37.54	Main material	1.405000	
	Nickel	7440-02-0	0.61	Main material	0.023000	
	Gold	7440-57-5	0.19	Main material	0.007000	
	Lead	7439-92-1	0.48	Main material	0.018000	
	Tin	7440-31-5	0.83	Main material	0.031000	
	Core	NA	44.54	Main material	1.667000	
	ABF	NA	15.70	Main material	0.588000	
	Solder mask	N/A	0.11	Main material	0.004000	

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Capacitor 1					0.041280	0.372
	Ceramic (BaTiO ₃)	N/A	61.80	Ceramic	0.025511	
	Inner electrode (Ni)	7440-02-0	27.00	Inner electrode	0.011146	
	Outer electrode (Cu)	7440-50-8	9.90	Outer electrode	0.004087	
	Plating 1 (Ni)	7440-02-0	0.40	Plating1	0.000165	
	Plating 2 (Sn)	7440-31-5	0.90	Plating2	0.000372	
Capacitor 2					0.039600	0.357
	Ceramic (BaTiO ₃)	N/A	67.40	Ceramic	0.026690	
	Inner electrode (Ni)	7440-02-0	17.00	Inner electrode	0.006732	
	Outer electrode (Cu)	7440-50-8	13.80	Outer electrode	0.005465	
	Plating 1 (Ni)	7440-02-0	0.50	Plating1	0.000198	
	Plating 2 (Sn)	7440-31-5	1.30	Plating2	0.000515	
Solder Balls					0.965679	8.706
	Tin (Sn)	7440-31-5	95.50	Main material	0.922224	
	Silver (Ag)	7440-22-4	4.00	Main material	0.038627	
	Copper (Cu)	7440-50-8	0.50	Main material	0.004828	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
11/02/09	1.0	Initial Xilinx release.
08/03/10	1.1	Updated average weight. Updated component percentage of total for all components. Added substances and corresponding data to ink and substrate components.
07/22/11	1.1.1	Change CAS# for N, N-dimethylformamide from 68-12-1 to 68-12-2
03/29/13	1.2	Updated Substrate Component.

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